

Gels *Dow Corning*[®] 3-4133 Dielectric Gel

FEATURES

- Clear
- Fast heat cure
- Long working time and low viscosity aid process flexibility
- Impregnation may be successful without vacuum

BENEFITS

- Fast heat cure for increased processing speeds
- Long working time at RT and low viscosity provide processing flexibility

2-part, clear, 1:1 mix ratio gel

TYPICAL PROPERTIES

Specification Writers: Please contact your local Dow Corning sales office or your Global Dow Corning Connection before writing specifications on this product.

Property	Unit	Value
Viscosity (Part A or Base)	cP	425
	mPa-sec	425
	Pa-sec	0.4
Viscosity (Part B or Catalyst)	cP	400
	mPa-sec	400
	Pa-sec	0.4
Viscosity (Mixed)	cP	450
	mPa-sec	450
	Pa-sec	0.4
Specific Gravity (Uncured Part A or Base)	-	0.97
Specific Gravity (Uncured Part B or Catalyst)	-	0.97
Working Time at 25°C (Pot Life - hours)	hr	6
Heat Cure Time @ 100°C	minutes	4
Heat Cure Time @ 125°C	minutes	2.2
Heat Cure Time @ 150°C	minutes	1.6
Gel Hardness	grams	600
Penetration	1/10 mm	10
Dielectric Strength	volts/mil	475
	kV/mm	19
Dielectric Constant at 100 Hz	-	2.87
Dielectric Constant at 100 kHz	-	2.86
Volume Resistivity	ohm*cm	4.7E+15

DESCRIPTION

Two-part gels offer more processing flexibility with the options of room-temperature with no need for ovens or heat-accelerated cure if faster processing is desired. These gels have been used extensively to seal and protect by coating, encapsulating or potting various electronic devices, especially those with delicate components. Gels are a special class of encapsulants that cure to an extremely soft material. Gels cure in place to form cushioning, self-healing resilient materials. Cured gels retain much of the stress relief and self-healing qualities of a liquid while providing the dimensional stability of an elastomer which is increasingly needed for delicate components. Gels have been used to isolate circuits from the harmful effects of moisture and other contaminants and provide electrical insulation for high voltages. Another use is providing stress relief to protect circuits and interconnections from thermal and mechanical stresses. Gels are usually applied in thick layers to totally encapsulate higher architectures. More recently, gels have found application in optoelectronics due to their stress relieving capability and high refractive index, as well as the stability of these properties over time.

MIXING AND DE-AIRING

Some gels are supplied in bladder packs that avoid direct air contact with the liquid gel components, allowing use of air pressure over the pack in a pressure pot for dispensing. Do not apply air pressure directly to the liquid gel surface (without the bladder pack) as the gel can become supersaturated with air and bubbling can occur when the material is dispensed and cured. Use of bladder packs prevents bubbling, maintains cleanliness and avoids gel contamination. Gels can be dispensed manually or by using one of the available types of meter mix equipment. Typically, the two components are of matched viscosities and are readily mixed with static or dynamic mixers, with automated meter-mix normally used for high volume processes. For low-

TYPICAL PROPERTIES, continued

Property	Unit	Value
Dissipation Factor at 100 hz	-	0.0004
Dissipation Factor at 100 kHz	-	0.000067
Linear CTE (by TMA)	ppm/°C	350
Shelf Life at 25°C	months	12

volume applications, manual weighing and simple hand mixing may be appropriate. Inaccurate proportioning or inadequate mixing may cause localized or widespread problems affecting the gel properties or cure characteristics. If possible, the potential for entrapment and incorporation of gas (typically air) should be considered during design of the part and selection of a process to mix and dispense the gel. This is especially important with higher-viscosity and faster-curing gels. Degassing at >28 inches (10-20 mm) Hg vacuum may be necessary to ensure a void-free, protective layer.

POT LIFE AND CURE RATE

Working time (or pot life) is the time required for the initial mixed viscosity to double at room temperature (RT). The cure reaction begins when Parts A and B are mixed. As the cure progresses, viscosity increases until the material becomes a soft gel. Cure conditions are shown in the typical properties table. Cure is defined as the time required for a specific gel to reach 90% of its final properties. Gels will reach a no-flow state prior to full cure. Addition-cure silicone gels may be RT and heat cure or exclusively heat cure. Adding heat accelerates the cure reaction. Additional time should be allowed for heating the part to near oven temperature. Cure schedules should be verified in each new application.

USEFUL TEMPERATURE RANGES

For most uses, silicone elastomers should be operational over a temperature range of -45 to 200°C (-49 to 392°F) for long periods of time. However, at both the low- and high temperature ends of the spectrum, behavior of the materials and performance in particular applications can become more complex and require additional considerations. For low-temperature performance, thermal cycling to conditions such as -55°C (-67°F) may be possible, but performance should be verified for your parts or assemblies. Factors that may influence performance are configuration and stress sensitivity of components, cooling rates and hold times, and prior temperature history. At the high-temperature end, the durability of the cured silicone elastomer is time and temperature dependent. As expected, the higher the temperature, the shorter the time the material will remain useable.

COMPATIBILITY

Certain materials, chemicals, curing agents and plasticizers can inhibit the cure of addition cure adhesives. Most notable of these include: Organotin and other organometallic compounds, Silicone rubber containing organotin catalyst, Sulfur, polysulfides, polysulfones or other sulfur containing materials, unsaturated hydrocarbon plasticizers, and some solder flux residues. If a substrate or material is questionable with respect to potentially causing inhibition of cure, it is recommended that a small scale compatibility test be run to ascertain suitability in a given

application. The presence of liquid or uncured product at the interface between the questionable substrate and the cured gel indicates incompatibility and inhibition of cure.

REPAIRABILITY

In the manufacture of electronic devices, salvage or rework of damaged or defective units is often required. Removal of Dow Corning dielectric gels to allow necessary repairs can be assisted by using Dow Corning® OS Fluids. Additional information regarding these products is available from Dow Corning. Digestive stripping agents, such as SU100 from Silicones Unlimited, can also be used. In addition, if only one component needs to be replaced, a soldering iron may be applied directly through the gel to remove the component. After work has been completed, the repaired area should be cleaned with forced air or a brush, dried, and patched with additional silicone gel.

PACKAGING

In general, Dow Corning dielectric gels are available in batch-matched kits containing both Part A and Part B components. Packages that are typically available include 210-mL dual cartridges, one-gallon pails, five-gallon pails and 55-gallon drums. Not all gels may be available in all packages, and some additional packages and package sizes may be available.

STORAGE AND SHELF LIFE

Storage conditions and shelf life ("Use By" date) are indicated on the product label.

HEALTH AND ENVIRONMENTAL INFORMATION

To support customers in their product safety needs, Dow Corning has an extensive Product Stewardship organization and a team of Product Safety and Regulatory Compliance (PS&RC) specialists available in each area. For further information, please see our website, www.dowcorning.com, or consult your local Dow Corning representative.

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These products are neither tested nor represented as suitable for medical or pharmaceutical uses.

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